



SPECIALTY CHEMICALS / HIGH PURITY, SOLVENT CLEANER

AmberClean™ 205



AmberClean™ 205 is a high purity, solvent cleaner formulated to replace highly flammable solvents in critical cleaning applications. AmberClean 205 has a low surface tension that facilitates the removal of process fluids, residues and other contaminants associated with electronic components such as read-write heads and printed circuit boards. It is conductive to prevent ESD damage to sensitive electronic devices. AmberClean 205 is not flammable and has low volatility. AmberClean 205 can be used in hand wipe, immersion or ultrasonic applications.

TYPICAL PHYSICAL PROPERTIES

Appearance	Clear, colorless liquid
Specific gravity, 20°C	0.84
Lbs/gallon	6.99
pH (1% in deionized water)	8.5
Surface tension	25.4 dynes/cm
Flash point	66°C, PMCC
Conductivity	200 µS/m
Water content, %	<0.20%

RECOMMENDED PROCESS PARAMETERS

AmberClean 205 should be used concentrated and should not be heated above its flash point. For final clean applications a final rinse with a microelectronics grade solvent, such as IPA, will produce a clean dry part. AmberClean 205 can be used in hand wipe, ultrasonic and immersion applications. It can also be used as a dwell bath between processes for devices sensitive to air or moisture.

AVAILABLE PACKAGING

55 gallon drums, 5 gallon pails, 1 gallon containers

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FEATURES AND BENEFITS

- Low surface tension of 25 dynes/cm facilitates surface wetting
- Cleans combinations of process fluids and their residues effectively
- Will not corrode Al, Ni, Fe or Co alloys, or Cu, Ta or Ru
- Conductive to prevent ESD damage to sensitive devices
- Contains no added water for critical PMR requirements
- Contains no corrosive anions, such as chloride, sulphate, or fluoride

SURFACE CONDITIONING

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